



Substrate handling & shipping , wetprocess, thin-film and photolithography products.

University brochure



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Index

- 03 Spin Processors
- 04 Spin Processors Options
- 05 SPIN Process Stations
- 06 Polos Precision Bake Plate
- 07 Atomic Layer Deposition System



03

Spin coaters

Suitable for all typical spin processes: cleaning, rinse/dry, coating, developing and etching.



09

PicoMaster UV direct laser writer

The highest degree of freedom to create micro structures in photo sensitive layers.

- 08 Mask Aligners
- 09 PicoMaster UV Direct Laser Writer
- 11 Mask, Reticle & Mechanical Picks

- 12 Vacuum & Die Handling
- 13 Spray Guns
- 14 Teflon® PFA and PTFE Process Cassettes



05

Spin Process Station System

Suitable for all typical spin processes: cleaning, rinse/dry, coating, developing and etching.



ALD Atomic Layer Deposition system

“Conceived by Dr. Phillipe de Rouffignac, the Harvard Center for Nanoscale Science’s (CNS) Principal Scientist in charge of thin film deposition”



07

ALD System

The highest degree of freedom to create micro structures in photo sensitive layers.

15 Metal Cassettes

16 Wafer Shipping Boxes & Canisters

17 Backlapping

18 Adhesive Films



16

Wafer Shipping & Storage

The most valuable product in the semiconductor and electronics industry.



08

Mask aligners

Align sustainability and economics in your next generation Mask Aligners without concessions to the resolution.

Mask Aligner

“I have been using the Midas mask aligner MDA-400LJ system for half a year, and I am quite happy to work with it. I think it is a good and affordable choice for labs which use photolithography occasionally and not dedicated to it.”

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Spin Processor

SPIN150i and SPIN200i

The versatile, high-quality natural polypropylene SPIN150i and SPIN200i single substrate spin coater are specifically designed for R&D and low volume production. Suitable for all typical SPIN processes: cleaning, rinse/dry, coating, developing and etching. Systems are also available in all-PTFE construction for specialist applications.

These well-proven models are ideal for processing a wide range of substrates from small fragments with a diameter of 5 mm up to 160 mm / 260 mm or square samples with dimensions 100x100 mm or 150x150 mm. Systems capable of up to 450 mm diameter are available.

SPIN150i Spin Coater



A-V36 vacuum chuck



System benefits:

- High speed acceleration up to 0 - 12,000 rpm in 0.3 sec.*
- A detachable touch screen control panel for use outside a glove box. (uses CAT5 cable)
- Programmable CW & CCW rotation enables specialist processes such as 'puddle' develop and/or etch.
- Engineering plastics, high quality seamless fabrication.
- Lid and bowl liner sets in anti-static PET.

** Depending on substrate size and chuck type*

Chucks

All spin coaters come standard with a chuck included. NPP material for standard units, PTFE for PTFE units. The SPIN150i for up to 150 mm substrates includes vacuum chuck A-V36 and fragment adaptor D-V10 (for 10 mm and up) for **FREE**.

Customized vacuum or mechanical chucks are available for almost any application. Chucks are available in the following materials: NPP with EPDM o-ring, PTFE, ECTFE, stainless steel, aluminum and other materials. Custom design spin processor chucks are available on request, please contact us for details.

Sol-gel coating

Spin coating is preferred for coating flat substrates with thin layers of material. Typically you spin coat photoresist on a semiconductor wafer, but our spin coaters are also used for spin coating polymer thin films like blockcopolymers (BCP) as PDMS and PMMA, or as a low-cost sol-gel method for spin-coated ZnO films, often on a glass substrate.

The units are operated via an easy to use, detachable colour touch-screen that offers intuitive programming and recipe storage. A variety of nozzles, megasonic cleaning and dispense lines can be added as options.



Spin Processor Options

Megpie

The sapphire MegPie is a single-wafer megasonic transducer for cleaning and sonochemical processing. It applies a uniform dose of acoustic energy to a rotating substrate. The MegPie will improve process efficiency and lower process time.



Applications:

- Post-CMP cleaning
- LIGA processes
- TSV processing
- Mask cleaning
- Pre-SOIC bond cleaning
- Etch assist
- SU-8 develop
- Plating pre-cleaning
- Lift off
- Pre-plating bubble removal
- Resist strip
- Post-laser cleaning



Other spinner options

Vacuum pump

The vacuum pump is quiet and reliable.



Dispense unit

Can be mounted in syringe holder and be connected to one of the 3 programmable dry contacts.



Syringe holder starter kit

Consisting of several 30cc dispense barrels, needles and plungers.



Center dispense system: opus

Quicker dispensing with higher reliability of results.

Centering tool

Easy to use centering tool is adjustable for different substrate sizes.



Central dispensing syringe holder

For single or triple syringes, with integrated N2 diffuser.



SPIN Process Station

An extremely versatile platform for a wide range of processes. Based on the proven high quality POLOS single substrate spin processor, the modular design spin process station provides excellent value for money: full plastic construction, with high-end components, compatible with any chemical environment in a modular set-up, suitable for your specific requirement.

The seamless integration of polypropylene (optional PTFE) spin processor in the base station allows you to work with all kinds of chemicals. In the station housing various modules can be incorporated and centrally controlled for supply of chemicals and gases.

Standard configurations are available for cleaning substrates as well as photomasks, photoresist coating, developing, etching and lift-off processes.



Source: Fraunhofer ENAS-Dr. Knut Gottfried, *Precise Bulk Silicon Wet Etching 2013*

Value for money

Fully automatic, accurate and repeatable processing:

Automatic linear dispense arm

- Freely programmable static, dynamic or oscillating chemical dispense.
- High pressure and/or megasonic cleaning directly to any point on the substrate. Static chemical dispense through a range of adjustable nozzles in the domed lid. Adjustable back - side spray arm. Heavy duty motor: programmable for 1 to 12,000 rpm. CW & CCW rotation allowing puddle mode.

Freely programmable process

- Sequentially programmable multiple dispense lines.
- Stepless programming of various flows within a process step from 150 up to 2500 mL/min (depending on dispense line thickness). For optional integrated mixing systems, the mixing rates of the various chemicals can be programmed per step.



POLOS Precision Bake Plate

The modular setup of this new table top hotplate enables easy plate (chuck) exchange and upgradeable options, making this a versatile and affordable tool for R&D and pilot lines. A precision digital temperature controller enables adjustable temperature steps of 1 °C up to 230 °C. It is suitable for soft bake as well as hard bake processes, and curing of photo resist, epoxy or any other work requiring precise temperature control.

Features

- Diagnostic serial interface (RS232)
- Precision temperature controlling system. Uniform temp.: +/- 0,5 °C
- Digital temperature controller: adjustable in steps of 1 °C
- Countdown timer (1-999 sec.) with acoustic alert

Options

- Hinged lid
- Proximity pins
- Lifting pins
- Vacuum bake



Measurement & Weight	HL200S
Weight:	12 kg
Dimensions device:	450 x 320 x 135 mm
Dimensions with Hinged Lid:	450 x 320 x 200 mm

Operational environments

The system is designed for an ambient temperature of 10 °C - 40 °C.



Features include

- Temperature ranges from 50 - 230 °C (adjustable in steps of 1 °C)
- Programmable storage of 10 programs (temperature/time)
- Temperature uniformity ± 0,5 °C
- Heater surface area 220 x 220 mm
- Suitable for 1 x 8" wafer
- Heater block material: aluminum (anodized) or PTFE coated
- CE-certification

Operating requirements:

Voltage:	110 or 240 VAC / 50/60 Hz
Max. current:	2,5 / 5 A
Power consumption (max.):	550 Watt

Atomic Layer Deposition System

Atomic layer deposition system

ALD technology has taken a leap in the past couple of years. SPS-Europe offers various systems, including a table top version for surface controlled layer-by-layer deposition with atomic layer accuracy.

Table top ALD systems

There is a need for deposition equipment optimized for growing conformal thin films at smaller scales at a reasonable cost. The AT400 4" system accomplishes these goals and fills a space in the market.

The AT-400 ALD system provides a solution to conformal, conductive thin films for 3D sample prep while also providing traditional 2D coatings that are currently grown using sputtering/evaporation. The AT400 not only pushes the boundaries, but is also an effective replacement for current sample preparation processes all within a benchtop configuration at a comparable price point.



Analog pressure controller for quick pressure check and pulse monitoring.

7" 16-bit color touchscreen HMI.

NEW! 6" systems also available! AT600

Large substrate and precursor temperature ranges

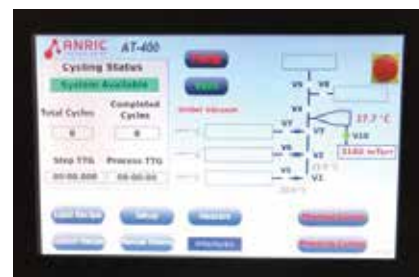
- Chamber temperatures from RT to 350 °C ± 1 °C
- Precursor temperatures from RT to 150 °C ± 2 °C with opt. heating jackets

Fast cycling capability

- 6-10 cycles/min or up to 1.2 nm/min of Al₂O₃ (best in class)

Up to five ALD precursor sources at one time

- Three (3) organometallic or other metal containing sources all up to 150 °C



7" touchscreen display with complete control over operation of the tool, recipe generation and sensor data. Easy to use and robust control SW interface



Glovebox integration

A standard AT400 can be attached to a glove box with a glove box adapter upgrade. The system is sealed to an open side of a pressurized or new glove box.

The deposition chamber and sample holder are completely sealed within the inert gas environment. Air sensitive materials and substrates can be handled and deposited with utmost confidence. 100% of the glove box floor and shelving will remain accessible after installation ALD system.



Mask Aligners

Manual mask aligner LED light source 4"

The MDA-400LJ is a mask aligner specially designed for university and research institutes. The system is equipped with a maintenance free 365 nm LED light source (50,000 hours lifetime) and therefore ideal for resist processing.



Manual mask aligner and exposure system 6"

The MDA-400M-6 is designed for research organizations who want to work with a state of the art technology mask aligner. This highly accurate system allows researchers to easily develop their processes on wafers up to 6".



Semi automatic mask aligner and exposure system 6"

The MDA-600S is widely used for MEMS, LED and Semiconductor industry. It can provide a higher performance of alignment accuracy and resolution. It is an ideal and economical tool for Universities and Research Centers.



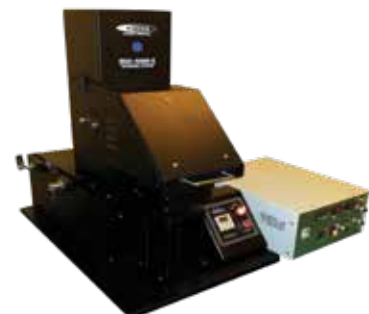
UV intensity meter (365 nm)

This hand-held digital UV intensity meter is suitable for measuring 365 nm (UV I-Line), 0 ~ 999.99 mW/cm² intensity as well as uniformity. By simply changing probe position and pressing "ENTER", the processor calculates UV beam average and uniformity (a five-point measuring is recommended). Meter comes with a built-in charger, and does not require a battery.



Manual UV exposure system 4"

The MDA-400M-E 4 inch exposure system is good for research and variable process of all applications. It represents next generation of full-field lithography systems.



Direct laser writer for maskless lithography

PicoMaster 100

- Compact table top design
- < 300 nm features
- Up to 4 x 4" substrates
- 375 nm source available for more demanding applications



UV direct laser writer

The PicoMaster is a versatile UV Laser Writer with ultra high precision components, specifically designed to give the user the highest degree of freedom to create micro structures in photo sensitive layers. The rasterizing principle of the machine ensures proper and constant exposure over the whole surface. Scanning the 4" substrate

at high speed and stepping the laser head with a software adjustable pitch.

- Highest resolution in the market with 405 nm laser
- Minimal maintenance costs
- Compact optical module: use a spare optical unit for revolutionary machine downtime reduction
- User-friendly operation



PicoMaster 200

- Stand alone system
- < 300 nm features
- Up to 8 x 8" substrates
- High quality tool & high quality output



Direct laser writer for maskless lithography

	PicoMaster 100	PicoMaster 200
Vacuum pump integrated		✓
Max substrates size	4 x 4 "	8 x 8 "
Control PC integrated		✓
Touchscreen controller		✓
Mechanical properties		
Stroke scan & step	Max. 115 mm	Max. 230 mm
Scan axis	Air bearings	Air bearings
Repeatability	< 40 nm	< 20 nm
Resolution	2 nm	2 nm
Scan speed	Max. 300 mm/s	Max. 450 mm/s
Straightness axis	< 0.5 µm over 105 mm	< 1 µm over 230 mm
Substrate thickness	0 - 4 mm manual adjustment.	0 - 4 mm manual adjustment.
Substrate size	Min. 5 x 5 mm, max. 110 x 110 mm.	Min. 5 x 5 mm, max. 220 x 220 mm.
Exposable area	Max. 105 x 105 mm (speed depended).	Max. 215 x 215 mm (speed depended).
Optical properties		
Laser	405 nm, GaN laser diode.	405 nm, GaN laser diode.
Selectable spot sizes	280 nm optional 490 nm or 880 nm FWHM.	280 nm optional 490 nm or 880 nm FWHM.
NA	0.85	0.85
Intensity	Max. 5 mW in the spot.	Max. 5 mW in the spot.
Grayscale control	4096 levels	4096 levels
Autofocus	800 Hz bandwidth red laser controlled ± 0.15 mm height variation with auto height tracking.	800 Hz bandwidth red laser controlled ± 0.15 mm height variation with auto height tracking.
Focus offset	Adjustable by software control.	Adjustable by software control.
Data rate	Standard 10 Mhz.	Standard 10 Mhz.
Performance specifications		
CD ¹	Min 0.3 µm	Min 0.3 µm
1 Critical Dimension of the PicoMaster strongly depends on process parameters, such as resist types and layer thickness.		
Intensity uniformityw	< 0.5 %	< 0.5 %
Address grid	Standard: 20 nm in scan direction and programmable in step direction.	Standard: 40 nm in scan direction and programmable in step direction.

Mask, Reticle & Mechanical Picks

Mask & reticle picks

Our line of photolithography mask & reticle picks and handling equipment are the result of years of work with semiconductor companies and mask shops to provide a non-contaminating secure means of handling photo masks. With the stringent cleanliness requirements for submicron applications today, SPS-Europe mask handling tools have become indispensable.



Features

- Tangential edge-grip only: no front or back face contact.
- Compatible with most pelliclized square reticles and round masks with flats.
- Minimal moving parts for simple cleaning and low particle generation.
- Lightweight, economical and easy-to-use with trigger-type gripping mechanism.
- V-type grippers allow masks with beveled edges to be loaded from flat surfaces.
- Various gripper widths and V-groove depths allow customizing for each application.

MCP- mechanical edge grip picks

These custom-fit, normally closed, outside diameter wafer edge handling tools provide clean constant-force handling from the edge exclusion zone of a substrate. Using high performance plastics and Kalrez® touch pads, these tools are highly customized for specific applications and are available for substrates of all sizes, materials and thicknesses.

PFA Sieves and Dipper

Resistant to most chemicals, PFA sieves and dippers are ideal for ultra-pure applications. They are non-wettable, heat resistant and easy to clean. Sieve and dipper can be used with containers that have openings of 80 mm or greater and a capacity ranging from 300 mL to 1000 mL. Overall size is 76 mm diameter and 180 mm length, including handle.

Dipper

- Can hold up to 2 square or round substrates.
- Dipper has a "V" shaped groove.
- Easy slide function for use of multiple sizes substrates.
- Chemically resistant to acids and bases.
- Also available in NPP.

Sieve

- Non-contaminating and resistant to most chemicals.
- Ideal for coarse sorting or draining of aggressive media.
- Handle hooks over edge of vessel for draining.



Vacuum & Die Handling



Vacuum wafer handling

We supply an extraordinary number of different types of vacuum tips for many different sizes, shapes, weights and materials of wafers, substrates, dies and packages and applications/equipment, as well as for a complete range of temperature and chemical environments. We recommend carbon filled PEEK (PolyEtherEther Ketone) tips for most applications, especially where ESD protection is a must.

Our T69-series anti-static PEEK all-purpose press-fit vacuum tips are suitable for standard wafer handling up to 140 °C - 160 °C. The T791, T792 and T794 are special versions for thin wafer handling with thin vacuum pockets.

We will design and fabricate vacuum tips to your specifications for your special requirements.

Extended range available - contact us for full details.

Die wafer handling

VCC die handling antistatic tips

Precision machined conductive and high temperature Vespel® rigid vacuum tips for handling of small devices. Note that the VCC tips should always be used with a vacuum source which is supplying CFM as the VCC does not conform to the part like a elastomer cup.



BNCS D die handling antistatic cups

Precision molded antistatic nitrile Buna-N soft elastomer vacuum cups for handling of small devices. Antistatic nitrile provides antistatic protection at an economical price.



Spray Guns

Spray guns (SG)

Our spray guns are constructed of virgin PTFE and polypropylene to provide them with a long life span in harsh acid corrosive environments. Due to their design and comfortable grip spray guns are quickly becoming the industry standard in semiconductor fab plants, wet benches and work processing stations. All the spray guns may be purchased individually or with a variety of fittings and hoses.

DI spray/rinsing guns

Max. operating pressure - 75 PSI
Media temperature range - 40 °F - 130 °F



Part no.	Description
SG-103	Standard spray gun with ½ FNPT inlet thread.
SG-102	Spray gun with ¾" FNPT inlet thread.
SG-101	SG-101 spray gun with ¼" FNPT inlet thread.

Note: add -FT for front trigger option.

Nitrogen guns (Nitro)

Our PTFE nitrogen guns (Nitro) can deliver maximum anti-corrosion protection wherever extreme chemical environments are used in the vicinity of nitrogen dispensing or drying. Like its companion, the DI water spray, Nitro is manufactured of the same durable materials to resist acid attacks.

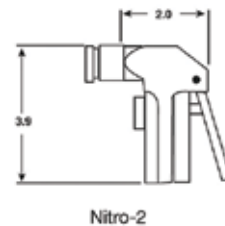
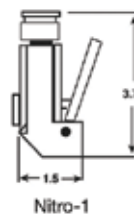


Nitrogen guns/drying guns

Max. operating pressure - 75 PSI
Media temperature range - 40 °F - 130 °F

Part no.	Description
Nitro-1	Standard nitrogen hand spray with ¼"FNPT inlet thread, filter housing with disposable filter.
Nitro-2	Same as Nitro 1 only using a standard spray gun body configuration.

Source part no.	Gun	Hose assy.	Fitting	Fitting
NITRO-3	NITRO-1	C4-PU	J44	J44
NITRO-3T	NITRO-1	C4-FEP	MC-F-44	MC-F-44
NITRO-4	NITRO-2	C4-PU	J44	J44
NITRO-4T	NITRO-2	C4-FEP	MC-F-44	MC-F-44



Note: add - FT for front trigger option (NITRO-4 and NITRO-4T only).



Teflon® PFA and PTFE Process Cassettes

Custom cassettes

SPS-Europe offers a full line of specialty plastic wafer cassettes for any application. Custom cassettes can be "PC" series cassettes are precision machined custom cassettes for special applications where off-the-shelf injection molded cassette varieties are either unavailable or under-performing. The majority of the "PC" cassettes are manufactured from PTFE Teflon® material, however, SPS-Europe also offers PFA cassettes.

PFA process cassettes

The PFA process cassettes are ideal for wet chemistry processing and are made to the industry standard designs. This makes them suitable as drop in replacement for your current PFA cassettes (other materials available). Optional laser marking is available.



**Cassette 2" 50 mm
PFA 25 slots**

ePB-2/50-25-R.1-eM-39-NAT



**Cassette 3" 76 mm
PFA 25 slots**

ePB-3/76-25-R.6-eM-39-NAT



**Cassette 4" 100 mm
PFA 25 slots**

ePB-4/100-25-R.9-eM-39-NAT



**Cassette 6" 150 mm
PFA 25 slots**

ePB-6/150-25-R.8-eM-39-NATe

**Cassette 6" 150 mm
PFA 25 slots**

ePB-6/150-25-R.10-eM-39-NAT



**Cassette 8" 200 mm
PFA 25 slots**

ePB-8-200-25-R.6-eM-39-NAT



PTFE custom process cassettes

SPS-Europe supplies chemical resistant custom cassettes for use in substrate and photo mask cleaning applications. Compatible fixed and detachable PTFE handles, lifter blocks and mechanical substrate handling tools are also available.

We offer stackable process boat storage boxes in many material options.

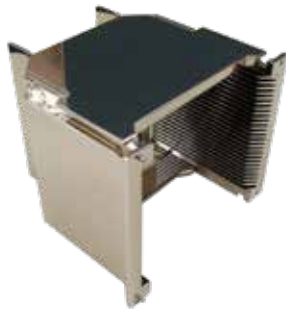
Metal Cassettes

Aluminum metal cassette

A popular all metal cassette replacement for plastic cassettes. The 150 mm or 200 mm all aluminum solid side wall metal cassette is designed for use in place of standard process plastic cassettes where temperature or dimensional stability of the plastic cassette is in question. SEMI standard MCF cassette features include robotic flanges, aluminum wafer support combs and vented screws. Construction is T6061 aluminum with stainless steel screws.

MCF

High temperature all aluminum cassette – plastic replacement



2851

Industry standard aluminum cassette with PTFE Teflon stops



MC1

Industry standard solid end wall version of 2851 style cassette



SQ22766

High temperature all aluminum process cassette

BAKE CASSETTES

All aluminum welded cassette for long bake-out cycling



SSC

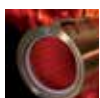
All welded stainless steel cassette for high temperature



Stainless steel cassette

For high temperature wafer bake applications or specialty applications, including megasonic and cleaning processes. All welded 316SST electro polished construction. Outside dimensions are similar to SEMI standard plastic process carriers. Transfer and automation compatible. Light Weight: standard SST 200 mm cassette ~ 2.5 lbs. Temperature: maximum recommended continuous operating temperature without causing distortion is 550 °C. Corrosion Resistance: 316SST offers better resistance than 302 and 304 SST; resists many industrial chemicals

and solvents including: sodium and calcium brines, hypo chlorite solutions, phosphoric acid, sulfite liquors, and sulfurous acids. Standard cassettes are designed for 50, 75, 100, 125, 150, 200, and 300 mm wafer configurations. Standard cassettes are designed for 75, 100, 125, 150 and 200 mm, 25-slot wafer configurations. Non standard 10, 12, 13, 26 and 28-slot cassettes, as well as carriers for square substrates and other non-standard diameters and wafer thicknesses are available upon request. Please contact SPS Europe for more information.



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Wafer Shipping Boxes & Canisters

Device protection and contamination control begins at the wafer fab and extends to the assembly site. SPS-Europe never forgets that the most valuable product in the semiconductor and electronics industry is also the most fragile and susceptible to mishandling and contamination. Not all wafers are created equal: with back-grinding, unique material sets, and exotic semiconductor processes, one product does not fit all wafers. From the most advanced eLX wafer canisters to cost efficient wafer jars, we offer tailor fit products to meet your requirements.



Single wafer shippers - coin style shippers

For 1, 2, 3, 4, 5, 6, 8 and 12 inch wafers, up to the 450 mm wafers, SPS-Europe has industry approved coinstyle or clamshell solutions.

Wafer Size	ePAK Description	Internal Diameter	Material	ePAK Order Code
1" (25 mm)	eCT1-25-ASSY-1-eM-08-NAT	25.4 mm	Natural PP	eWB0091-ASSY-1
1.5" (38 mm)	eCT1.5-38-ASSY-1-eM-08-NAT	39.6 mm	Natural PP	eWB0325-ASSY-1
2" (50 mm)	eCT2-50-ASSY-1-eM-08-NAT	52 mm	Natural PP	eWB0021-ASSY-1
2.5" (63 mm)	eCT2.5-63-ASSY-1-eM-08-NAT	65.5 mm	Natural PP	eWB0328-ASSY-1
3" (76 mm)	eCT3-76-ASSY-1-eM-08-NAT	78.6 mm	Natural PP	eWB0022-ASSY-1
4" (100 mm)	eCT4-100-ASSY-1-eM-08-NAT	104 mm	Natural PP	eWB0024-ASSY-1
5" (125 mm)	eCT5-125-ASSY-1-eM-08-NAT	127 mm	Natural PP	eWB0060-ASSY-1
6" (150 mm)	eCT6-150-ASSY-1-eM-08-NAT	152 mm	Natural PP	eWB0025-ASSY-1

Wafer shipping boxes

For 1, 2, 2.5, 3, 4 and 6 inch wafers, up to 150 mm wafers. Designed to hold multiple wafers by the edge.



Wafer Size	ePAK Description	Internal Diameter	Material	ePAK Order Code
1"	eMS-1/25.4-25-R.1-ASSY-1-eM-08-NAT	25.4 mm	Natural PP	eWB0302-ASSY-1
2"	eMS-2/50-25-ASSY-1-eM-08-NAT	50 mm	Natural PP	eWB0028-ASSY-1
2.5"	eMS-2.5/61.75-25-ASSY-1-eM-08-NAT	61.75 mm	Natural PP	eWB0105-ASSY-1
3"	eMS-3/76-25-ASSY-1-eM-08-NAT	76 mm	Natural PP	eWB0029-ASSY-1

Process boats

For 2, 3, 4, 6 and 8 inch wafers, up to 200 mm wafers. The process boats are easy and safe for handling of wafers and are design with open or closed slot.



Backlapping

Wafer backlapping film applicators

Model UH108 and model UH108-8 wafer backlapping film applicators are the ideal benchtop solution for your frontside protection tape application requirements. They offer a high degree of repeatable accuracy and are capable of cutting the film to the edge of the wafer, including the alignment flats, within 0.005 inches in less than 20 seconds. The standard model UH108 can accommodate 3, 4, 5 and 6 inch wafers.



Model UH108

Semi-automatic wafer/frame film applicator

The model UH115 features a semi-automatic one-pass lamination which provides an extra margin of safety when mounting particularly fragile wafers /substrates. Most mounters laminate the film in two passes, i.e. one pass as the film is laminated to the film frame and wafer/substrate and a second relaminating pass as the roller returns to its home position. The model UH115, however, laminates on the first pass only; the second pass is contact-free.



Model UH115

Features

- Static Ionization bar w/power safety interlock.
- Motor-assisted film feed.
- Take-up roller assembly.
- Single-pass lamination.
- Adjustable motorized roller speed and pressure.
- Workstage height adjustable from top of unit.
- Accommodates film/protective layer wound on the outside or inside.

Die matrix expander

The model UH130 accommodates up to 300 mm wafers/ film frames and features a 3 inch stroke with speed control and adjustable ram height. The heated wafer ram is regulated by a digital temperature controller and stops at a user preset height, resulting in consistent repeatability of expansion. The unit features a compact table top form factor and is extremely easy to operate.



Model UH130

Hoop rings

We also supply a full range of hoop rings, film frames and film frame shippers available from stock.



Hoop rings



Adhesive Plastic Films

Silicone-free

Silicone-free adhesive plastic films contain absolutely NO silicone release agents, resulting in a much cleaner process and more consistent adhesive properties. They share both the same linear elongation properties and uniformity of base film as well as adhesive properties similar to our other film lines.



Silicone-free

Standard UV

UV adhesive plastic films have the advantage of high adhesive strength - for the securing of wafers/suistrates during sawing - which becomes significantly reduced after UV light exposure, to facilitate die removal. This tape provides an ideal media for thin waferdicing, followed by gentle die removal. We are proud to offer the widest selection of UV film available to meet even your most stringent process requirements.



Standard UV

Antistatic UV

Antistatic UV adhesive plastic films are the best choice when your process requirements are most demanding. For static-selective devices, do not let ESD become a process variable. The antistatic layer dissipates negative charge build-up, typically resulting from removal of the protective backing film from the adhesive/base film, or during wafer mounting, sawing, etc. Additionally, the antistatic UV adhesive plastic film series share the same benefits as our standard UV films.



Antistatic UV



Almost 30 years of quality service and products

For almost 30 years SPS-Europe has offered quality products and services as a one-stop shopping point for front-end semiconductor manufacturers and related industries. We supply a range of industry leading products used worldwide for Wafer Handling, Wet Processing, Photolithography, OEM Replacement parts and the Solar industry. Dedication towards our customers and flexibility

in finding the right solution, combined with solid application knowledge and fast supply logistics, are the keywords of our service. SPS-Europe B.V. is a full-service distributor offering full-time service engineer support for the systems we supply. We manufacture our own SPIN150™ and POLOS™ spin coating systems - widely installed across the world.

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